

Features

- High Voltage, Higher Current Diodes in Subminiature Package
- Utilizes DTI's High Performance XOE™ Technology
- Molded Plastic Body, ANSI/UL94 V-0 Rated Material

Specifications¹

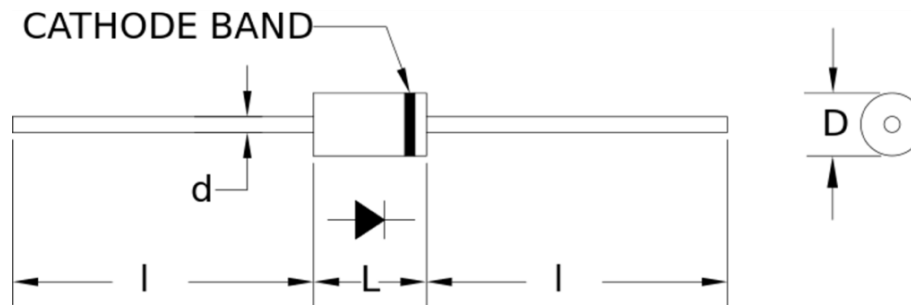
Part Number	V _{RRM} V	I _{FAVM1} mA	I _{FAVM2} mA	V _F V	I _R μA	I _{FSM} A	C _J ² pF	T _{RR} nS	R _{θJA} °C/W	E _{RSM} mJ	L in.	D in.	d in.	I in.
XNV02	2000	250	130	5.4	0.02	5	2.8	70	150	30	0.12	0.08	0.02	1.0
XNV03	3000	200	100	7.1	0.02	5	2.3	70	150	40	0.12	0.08	0.02	1.0
XNV04	4000	160	80	9.1	0.02	5	1.7	70	150	50	0.12	0.08	0.02	1.0
XNV05	5000	120	60	10.3	0.02	5	1.4	70	150	60	0.12	0.08	0.02	1.0

Temperature °C	
Operating Temperature	-55 to 125
Storage Temperature	-55 to 175
Maximum Junction Temperature	125

¹125°C ambient temperature unless stated otherwise.

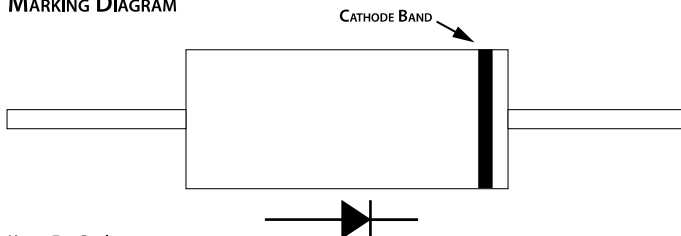
²Check Specification Definitions for conditions details.

Drawings

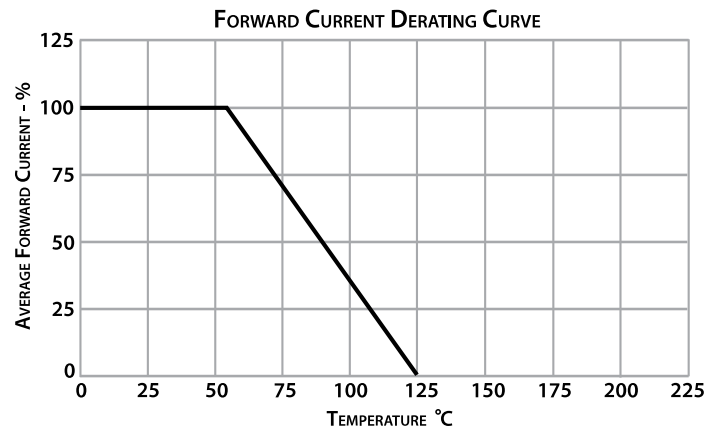


Dimensions in inches, tolerances ±0.020 except as noted

MARKING DIAGRAM

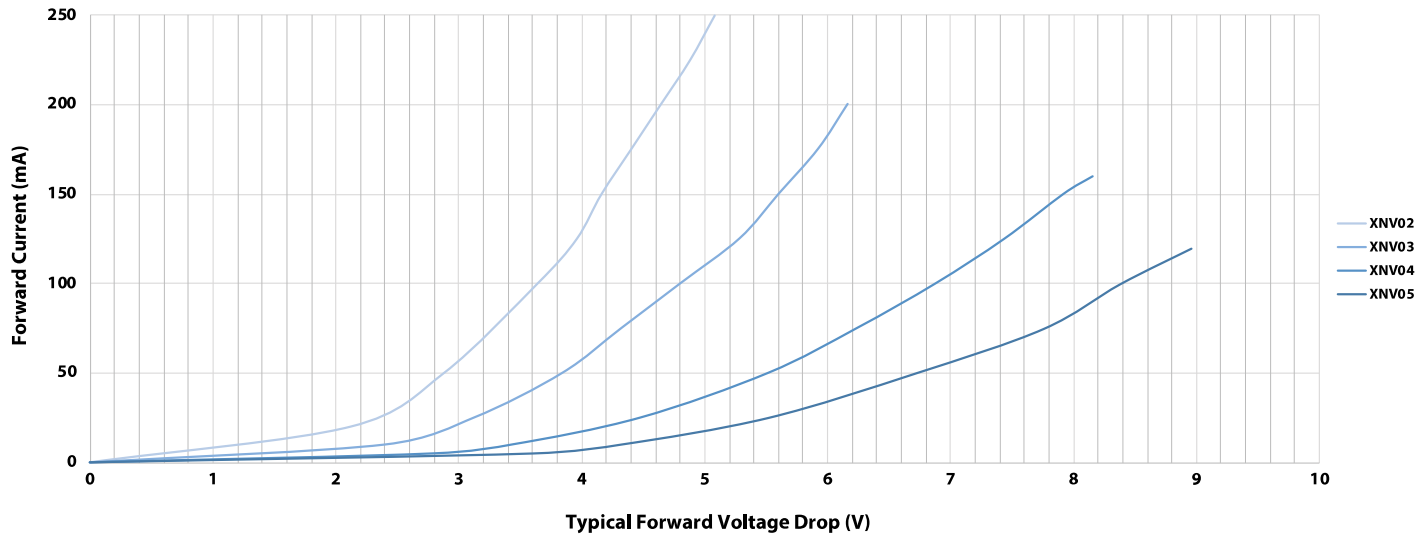


MARKING TYPE: RED, INKJET
(MARKINGS WILL WRAP ENTIRE BODY OF DIODE AND ARE SUBJECT TO MINOR CHANGES)



XNV SERIES

Forward Current vs. Typical Forward Voltage Drop, $T_A = 25^\circ\text{C}$
XNV Series



Specification Definitions

Specifications		Conditions
V_{RRM}	Maximum Repetitive Reverse Voltage	-
I_{FAVM1}	Maximum Average Forward Current	At $T_A = 55^\circ\text{C}$, in Oil
I_{FAVM2}	Maximum Average Forward Current	At $T_A = 55^\circ\text{C}$
V_F	Maximum Forward Voltage Drop	At I_{FAVM1} , $t_{PW} = 100\mu\text{sec}$
I_R	Maximum Leakage Current	At V_{RRM}
I_{FSM}	Maximum Surge Current	At 8.3mS, Single Half Sine
C_J	Typical Junction Capacitance	At $V_R = 4\text{VDC}$, $f = 1\text{MHz}$
T_{RR}	Maximum Reverse Recovery Time	$I_F = 0.5 I_{FAVM1}$; $I_R = -I_{FAVM1}$; $I_{RR} = -0.25 I_{FAVM1}$
$R_{\theta JA}$	Typical Thermal Resistance	Junction to Ambient, in Air
E_{RSM}	Maximum Reverse Energy Withstand	-

Note: Specifications subject to change without notice. Photo is representation only.

